



2022 JOINT INTERNATIONAL CONFERENCE ON NANOSCIENCE & NANOENGINEERING

Nanoscience and Nanoengineering for Nation's Growth and Sustainability

Website: <https://bond21.unimap.edu.my> Email: bond21@unimap.edu.my

PUTRA BRASMANA HOTEL

PEKAN KUALA PERLIS, 02000 KUALA PERLIS, PERLIS, MALAYSIA

22 - 23 SEPT 2022

CALL FOR PAPERS

SUBMIT VIA EMAIL:
bond21@unimap.edu.my



BOND21 is an International Conference on Nanoscience and Nanoengineering, hosted by the Institute of Nanoelectronic Engineering (INEE), UniMAP. BOND21 strives on the aspect of binding and bonding nanoscience and nanoengineering in creating high performance materials and devices with optimum cost through deep understanding on the theoretical framework and application principles. BOND21 also strives on maintaining and sustaining clean environment for future generation by promoting environment friendly and renewable aspects in the design and production of the materials and devices. BOND21 hopes to deliver enormous benefits to academicians, engineers and the community at large. It has been firstly hosted in 2013 which attracted more than 200 local and international participants. The 2nd BOND21 conference was also equally successful where it was organized in Bandung, Indonesia from 27th to 28th of July 2018. A similar scenario is anticipated for this year's BOND21 2022 with the conference will be organized in **hybrid mode**, offering both physical and virtual presentations.

TOPICS

Theory, simulation, design, fabrication, synthesis, processing technology, characterization & testing for:

- **Nanoscience** in the fields of physics, chemistry, biology, biotechnology, semiconductor material, device and process, sensors, superconductor, renewal energy, thin film, material science & electronics.
- **Nanoengineering** in the field of nanomaterial & nanoelectronics engineering.

IMPORTANT DATES



Full Paper Submission
01 July 2022



Notification of Acceptance
15 July 2022



Camera-Ready Paper Submission
29 July 2022



Registration & Payment
19 August 2022

REGISTRATION FEES

LOCAL	MYR 780 MYR 650
INTERNATIONAL	USD 185 USD 155

International Journal of Nanoelectronics and Materials

Accepted papers will be published in Scopus-indexed **AIP Conference Proceeding** and **International Journal of Nanoelectronics and Materials*** (*applied to selected papers only)

AIP | Conference Proceedings



UNIVERSITI
MALAYSIA
PERLIS



INSTITUTE OF
NANO ELECTRONIC
ENGINEERING

